ANNUAL GENERAL MEETING OF SHAREHOLDERS

April 23, 2026

Safe Harbor Statement

This presentation contains statements about management's future expectations, plans and prospects of our business that constitute forward-looking statements, which are found in various places throughout the presentation, including, but not limited to, statements relating to expectations of orders, net sales, product shipments, expenses, timing of purchases of assembly equipment by customers, gross margins, operating results and capital expenditures. The use of words such as “anticipate”, “estimate”, “expect”, “can”, “intend”, “believes”, “may”, “plan”, “predict”, “project”, “forecast”, “will”, “would”, and similar expressions are intended to identify forward-looking statements, although not all forward-looking statements contain these identifying words. In addition, the financial guidance set forth under the heading “Outlook” contains forward-looking statements. While these forward-looking statements represent our judgments and expectations concerning the development of our business, a number of risks, uncertainties and other important factors could cause actual developments and results to differ materially from those contained in forward-looking statements, including any inability to maintain continued demand for our products; failure of anticipated orders to materialize or postponement or cancellation of orders, generally without charges; the volatility in the demand for semiconductors and our products and services; the adverse impacts on the global economy, financial markets, global supply chains and our operations as well as those of our customers and suppliers arising from the COVID-19 pandemic ; failure to develop new and enhanced products and introduce them at competitive price levels; failure to adequately manage costs and expenses in line with revenue; loss of significant customers, including through industry consolidation or the emergence of industry alliances; lengthening of the sales cycle; acts of terrorism and violence; disruption or failure of our information technology systems; consolidation activity and industry alliances in the semiconductor industry that may result in further increased customer concentration, inability to forecast demand and inventory levels for our products; the integrity of product pricing and protection of our intellectual property in foreign jurisdictions; risks, such as changes in trade regulations, conflict minerals regulations, currency fluctuations, political instability and war, associated with substantial foreign customers, suppliers and foreign manufacturing operations, particularly to the extent occurring in the Asia Pacific region where we have a substantial portion of our production facilities; potential instability in foreign capital markets; the risk of failure to successfully manage our diverse operations; any inability to attract and retain skilled personnel, including as a result of restrictions on immigration, travel or the availability of visas for skilled technology workers; and the other risks detailed in the Risk Management section of our Annual Report. We expressly disclaim any obligation to update or alter these forward-looking statements for revisions or changes whether as a result of new information, future events or otherwise after the date of this release.

In addition, the United States and other countries have recently levied tariffs and taxes on certain goods and could significantly increase or impose new tariffs on a broad array of goods. They have imposed, and may continue to impose, new trade restrictions and export regulations. Increased or new tariffs and additional taxes, including any retaliatory measures, trade restrictions and export regulations, could negatively impact end-user demand and customer investment in semiconductor equipment, increase Besi’s supply chain complexity and manufacturing costs, decrease margins, reduce the competitiveness of our products or restrict our ability to sell products, provide services or purchase necessary equipment and supplies. Any or all of the foregoing factor could have a material and adverse effect on our business, results of operations or financial condition. In addition, investors should consider those additional risk factors set forth in Besi's annual report for the year ended December 31, 2025, and other key factors that could adversely affect our businesses and financial performance contained in our filings and reports, including our statutory consolidated statements. We expressly disclaim any obligation to update or alter our forward-looking statements whether as a result of new information, future events or otherwise.

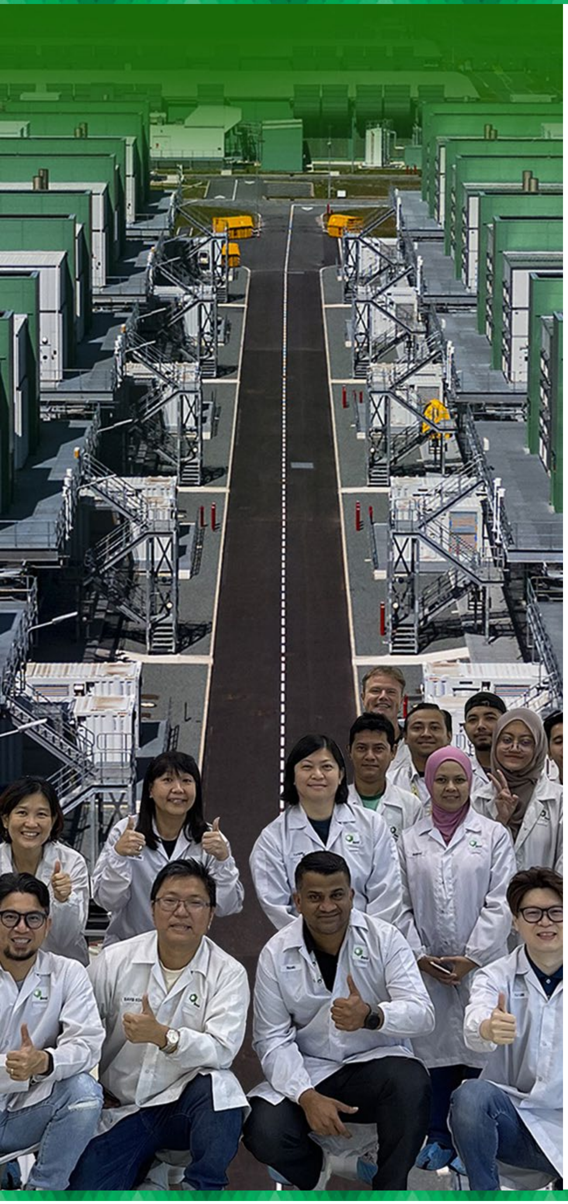
Agenda

I. Company Overview

II. Market

III. Sustainability

IV. Financial Review



I. COMPANY OVERVIEW

2025 Strategic Highlights

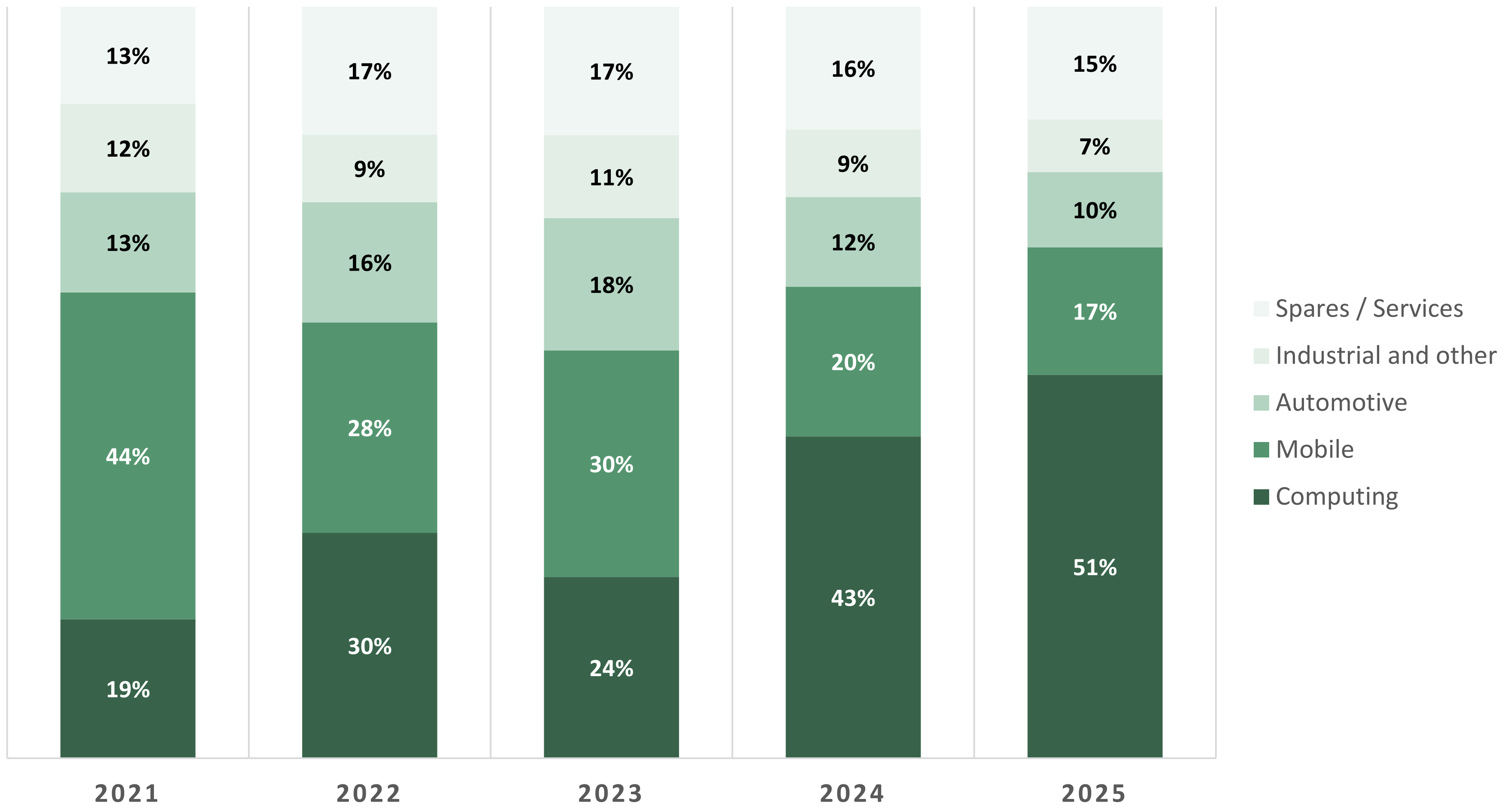
Besi

- ✓ Strategic plan updated to include new revenue and cost initiatives. Increased revenue target from € 1 billion+++ to € 1.5 - € 1.9 billion
- ✓ Continued progress on wafer level assembly agenda:
  - ✓ Hybrid bonding adoption grew to 150+ cumulative orders and 18 customers
  - ✓ New use cases identified for ASIC devices and co packaged optics
  - ✓ New hybrid prototype system completed with 50nm accuracy and increased throughput
  - ✓ First integrated hybrid bonding production lines installed
  - ✓ TC Next adoption expanded to 5 customers and multiple end markets
- ✓ Expansion of cleanroom capacity and Asian support to aid advanced packaging growth
- ✓ New products introduced for next gen AI applications and next market upcycle
- ✓ Substantial progress achieved versus 2026 sustainability targets

Key Financial Highlights 2025

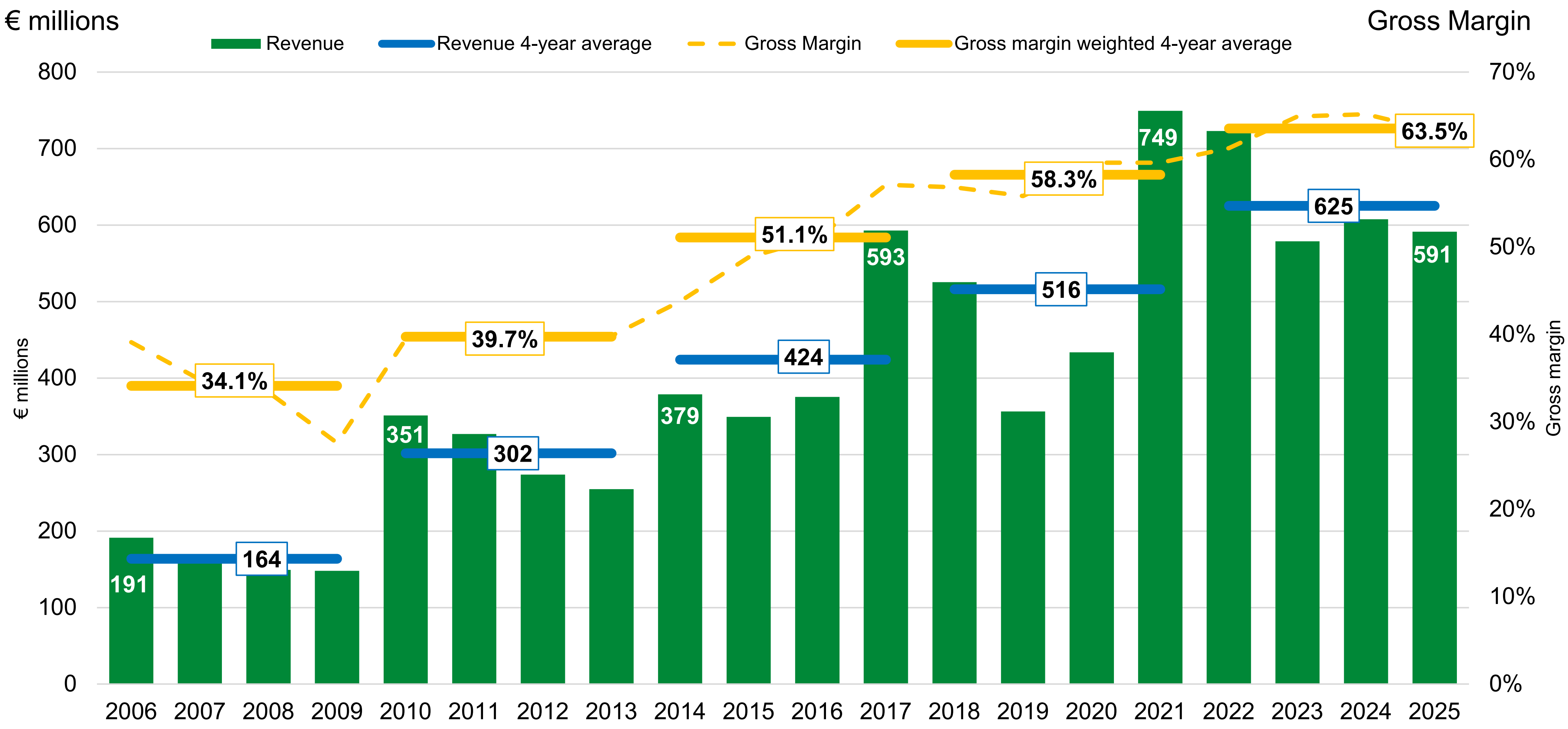
€ millions except % and EPS	**2025**	2024	*2025/24 Variance*
Revenue	**591.3**	607.5	*-2.7%*
Orders	**685.0**	586.7	*+16.8%*
Gross Margin	**63.3%**	65.2%	*-1.9pts*
Net Income	**131.6**	182.0	*-27.7%*
Net Margin	**22.3%**	30.0%	*-7.7pts*
EPS (Basic)	**1.66**	2.31	*-28.1%*
Return on Average Equity	**28.7%**	39.4%	*-10.7pts*
Net Cash	**36.0**	143.8	*-107.8*

AI Computing Applications Most Important Revenue Growth Driver



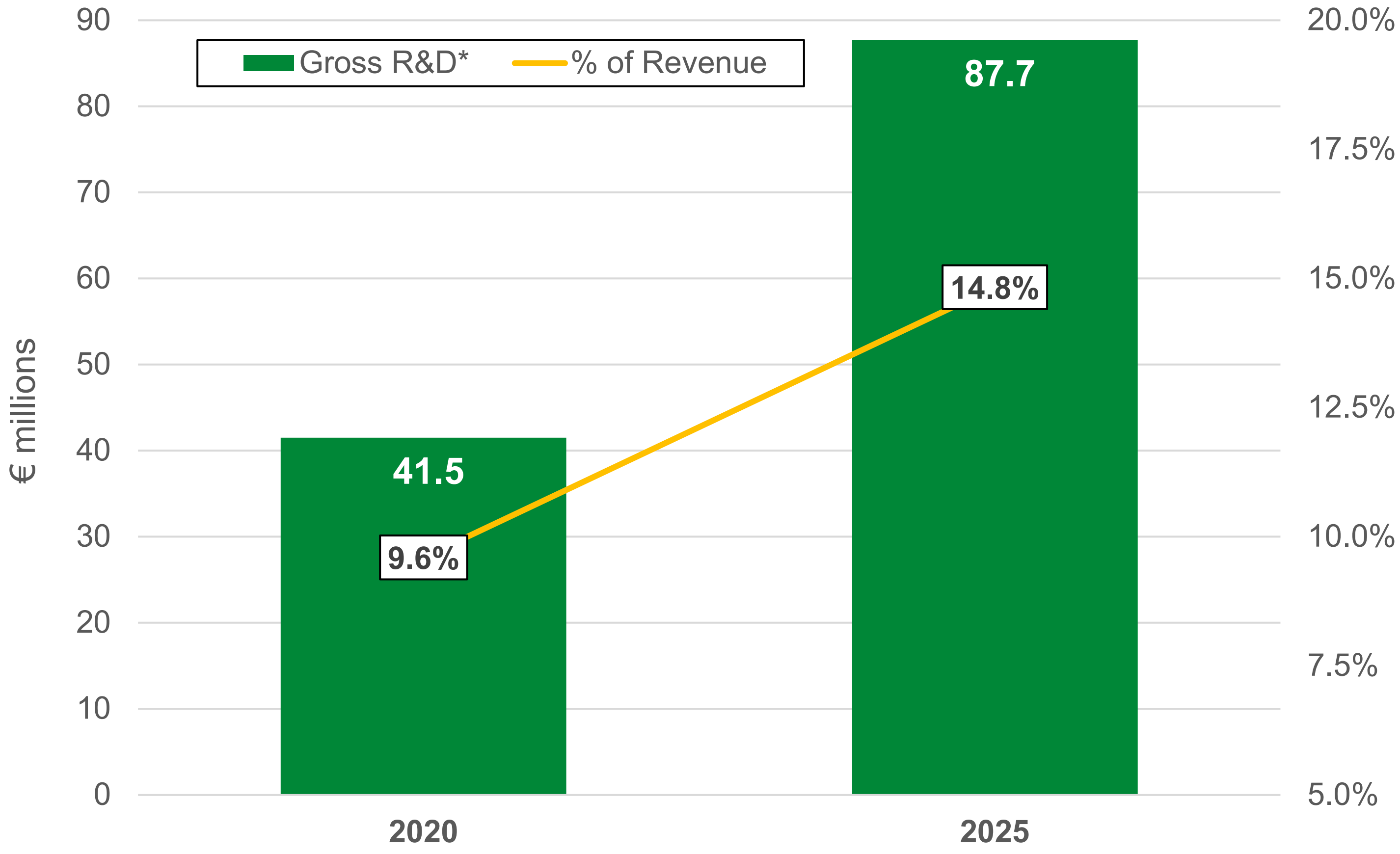
End market as % of total revenue

Higher Through Cycle Revenue and Gross Margin Trends



Focus on New Product Innovation

R&D investment has more than doubled since 2020



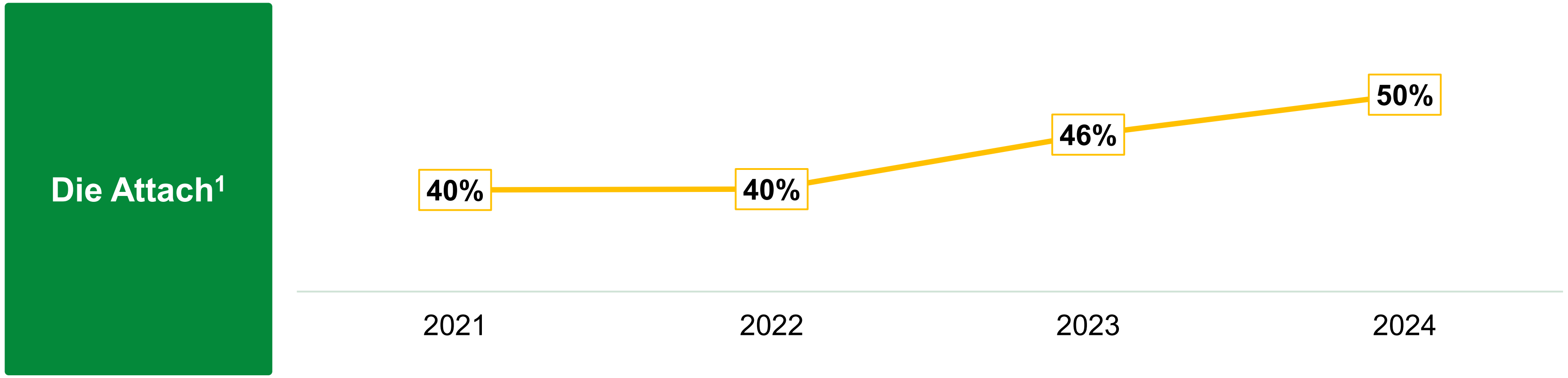
* Gross R&D spending excludes impact from capitalization/amortization of R&D costs

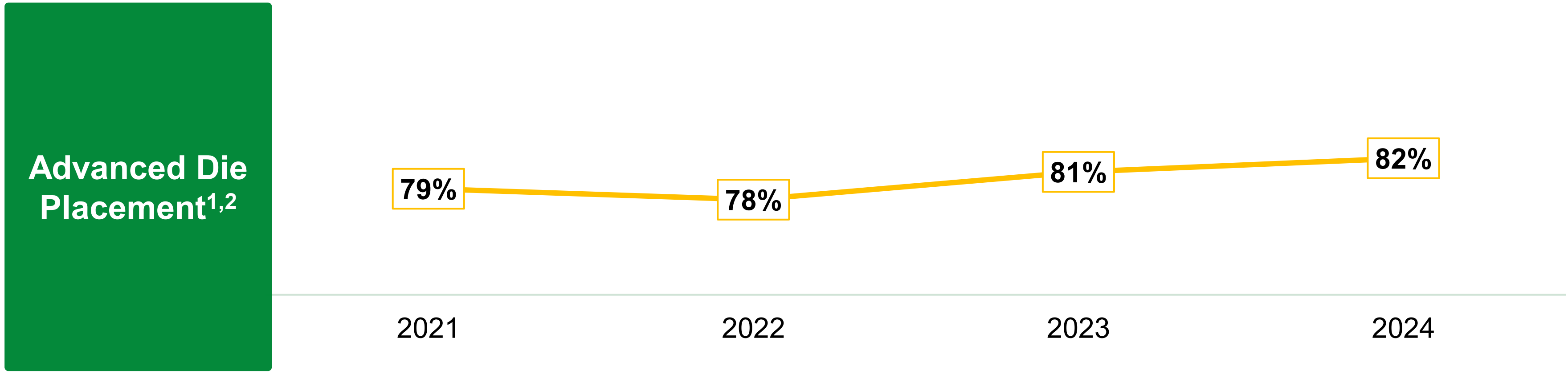
Innovation is a key driver of our business:
- New opportunities for each next-generation advanced packaging system

Significant R&D investment in advanced packaging over past 5 years to support:
- New 2.5D/3D IC assembly structures for AI
- Portfolio enhancements for next market upcycle

Key areas of current focus:
- 50 nm accuracy hybrid bonder
- TC Next for memory, logic and photonics applications
- Next generation flip-chip bonder for 2.5D and CoWoS
- 1 µm accuracy Evo for photonics

Leading Market Shares in Besi's Key Die Attach Markets



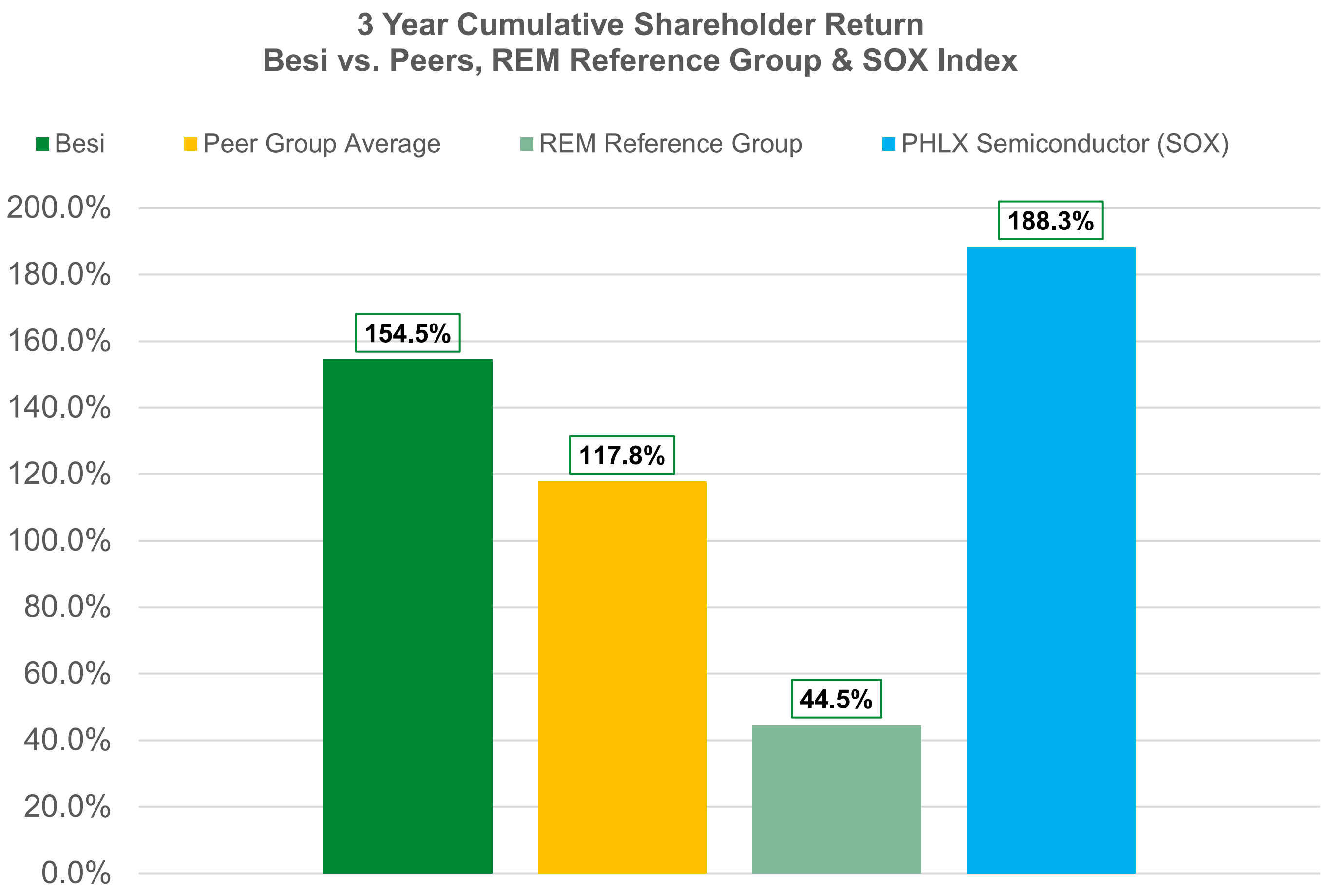


(1) Excludes TCB, wire bonding, dicing, and other.

(2) Advanced die placement defined as < 7 micron accuracy per TechInsights.

Source: TechInsights, December 2025

3 Years Cumulative TSR Outperformance vs. Peers



- Total Shareholder Return includes reinvestment of dividends
- Besi returns calculated in EUR. Philadelphia SOX returns calculated in USD
- Peer group average consists of Kulicke & Soffa, ASM PT, and Disco Corp

Source: S&P Capital IQ, PwC

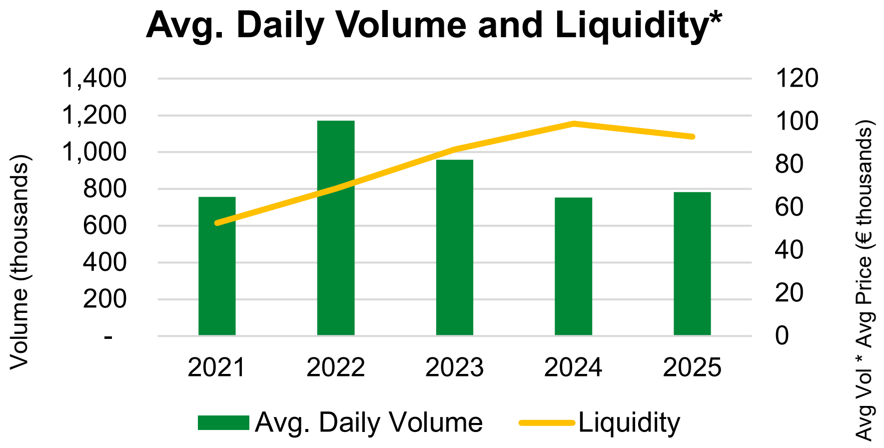
- Besi's total shareholder return in 2025 was 3.4%
  - Vs. 6% for peer group average
  - Up 68% from low point reached in April 2025
- Superior long-term total returns to shareholders (for period ending Dec 31, 2025)
  - 3yr: 155%
  - 5yr: 216%
  - 10yr: 2,076%

Besi's Stock is Highly Liquid. Shareholdings Have Migrated from NL to US/UK over Past 10 Years

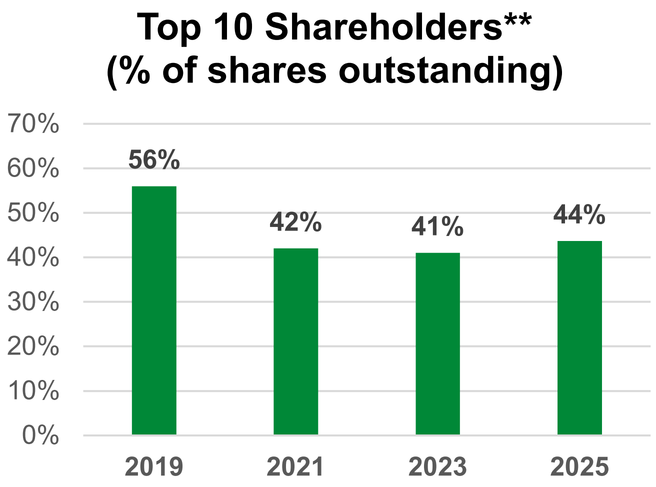
Besi

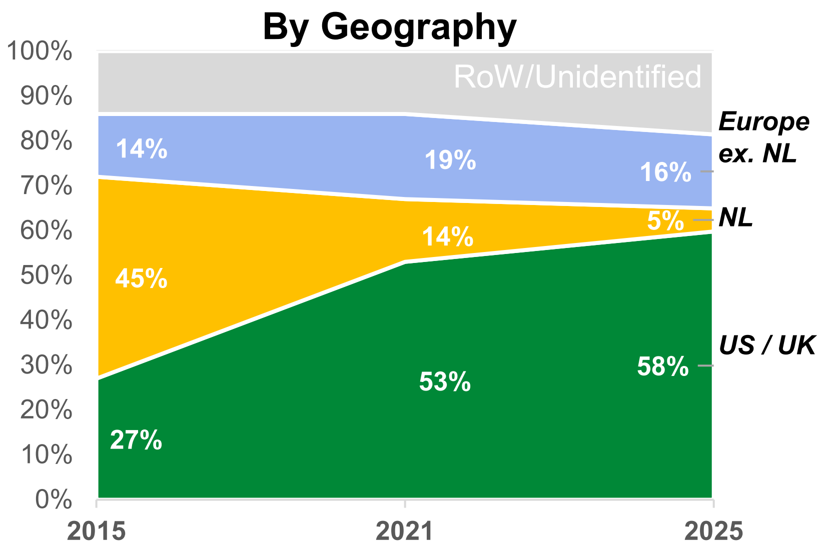
Market Profile

Symbol/ Index	• BESI • Euronext AEX
Market Cap*	• € 10.6 billion ($ 12.5 billion)
Dividend Policy	• Pay out 40-100% of net income per annum



Share Ownership

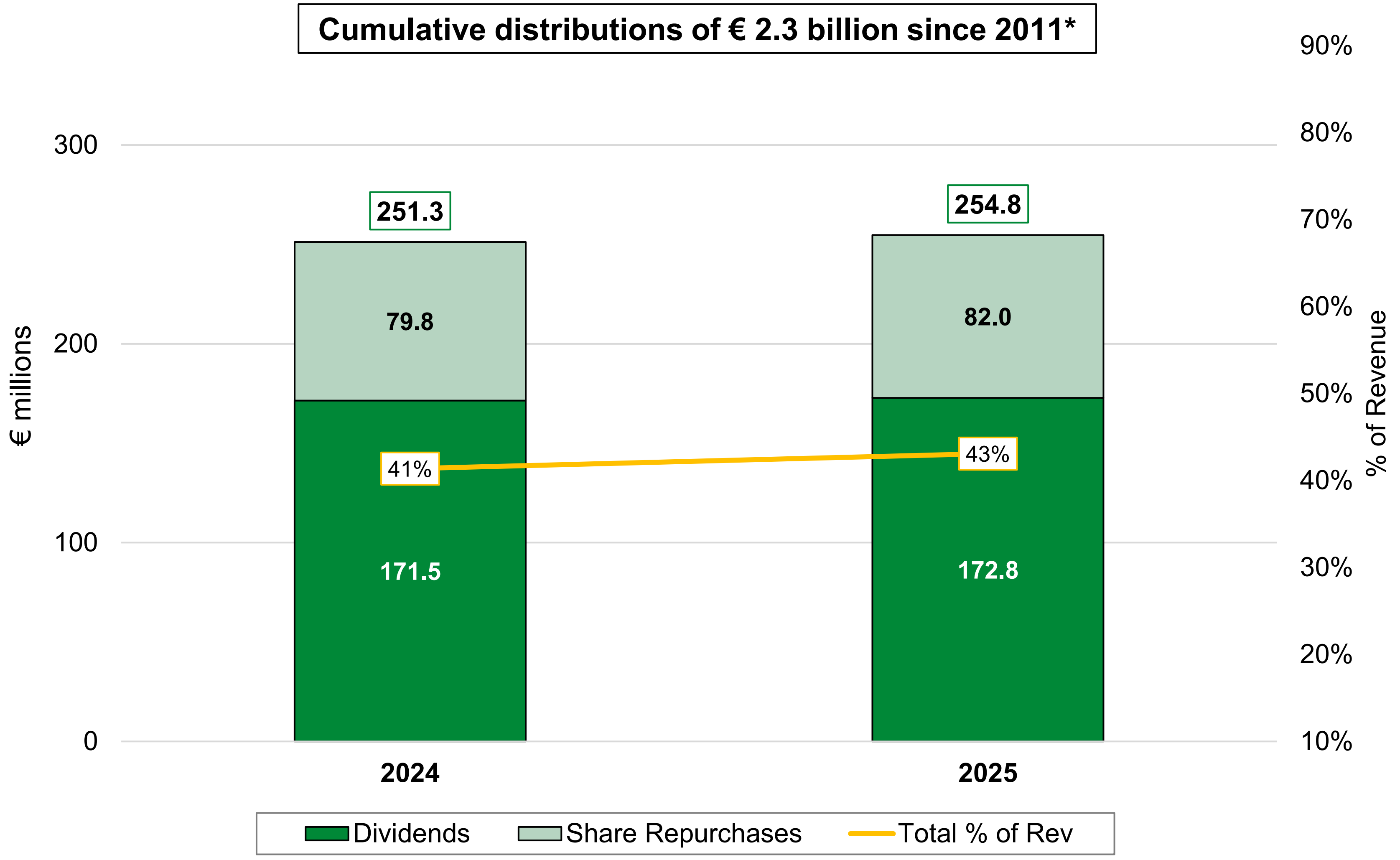




Share ownership is based on information per AGM of presented year

* As of December 31, 2025 ** Besi estimates

Attractive Capital Allocation Policy Continues



- **€ 254.8 million distributed in 2025**
- **€ 100 million share repurchase program completed:**
  - ~0.9 million shares purchased
  - Average price: € 114.83 per share
- **New € 60 million share repurchase program:**
  - € 11.3 million purchased in 2025 at average price of € 135.31 per share
- **Treasury shares equal 2.3% of TSO**
- **€ 1.58 dividend proposed for AGM approval. 95% pay-out ratio**

Key Business Model Objectives

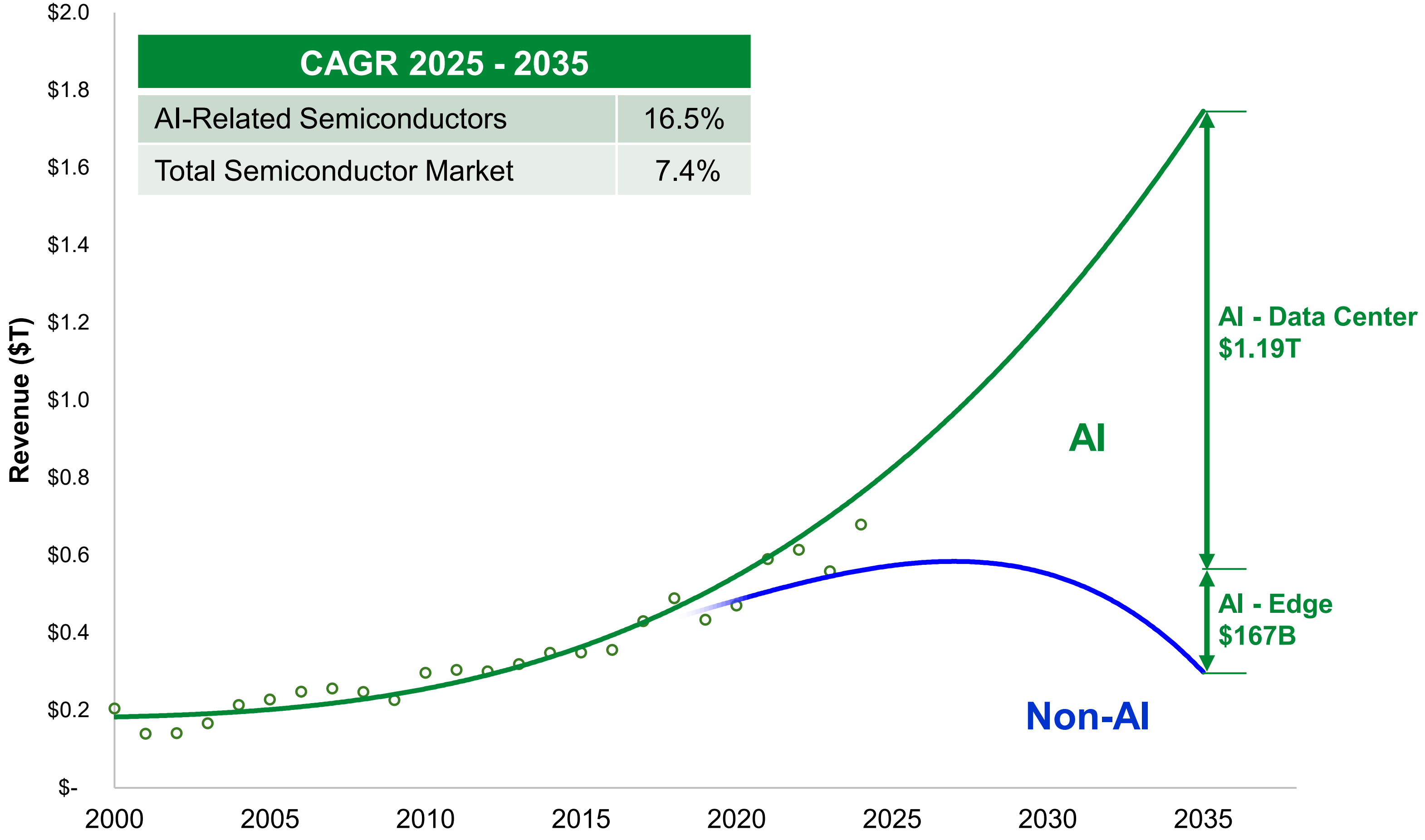
	Long Term Target
Revenue	€ 1.5 - € 1.9 billion
Addressable Market Share	40%+
Gross Margin	64 - 68%
Operating Margin	40 - 55%
Scope 1 & 2 Emissions	Net Zero GHG by 2030
Global Energy Needs	100% from renewable sources

II. MARKET

AI Driving Long-Term Semiconductor Revenue Growth

Total Semiconductor Revenue ($Trillion)

CAGR 2025 - 2035	
AI-Related Semiconductors	16.5%
Total Semiconductor Market	7.4%



Source: TechInsights, December 2025

Humanoid robotics

Autonomous vehicles

AI wearables (AR/VR)

AI smartphones

AI personal computers

Datacenter AI infrastructure

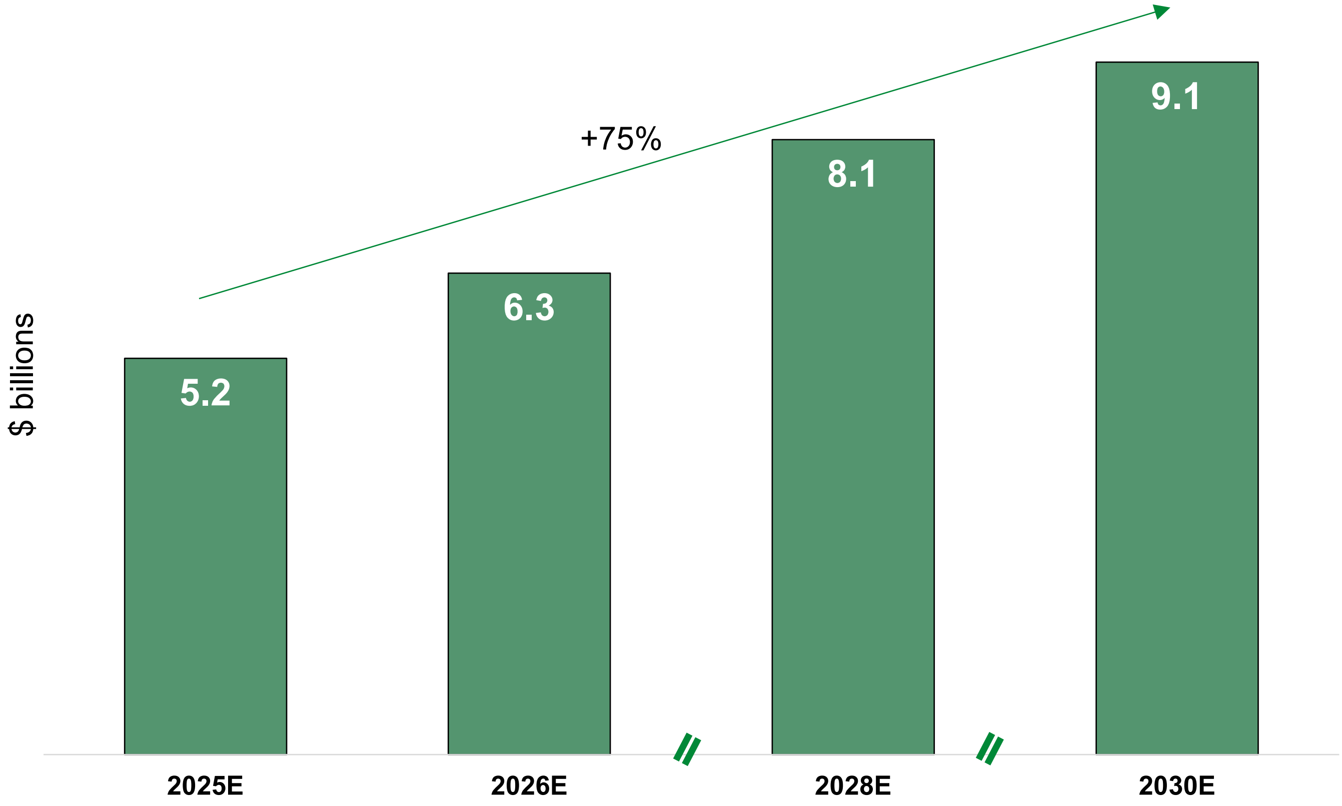
Many New Advanced Packaging Fabs Planned

Approximately $100B investment in progress or planned

Packaging Fab Projects	# Projects	Cost ($B)
Taiwan	4	26.1
USA	6	24.5
Europe	4	9.3
Korea	2	9.1
Singapore	1	7.0
China	7	6.3
India	2	6.0
Malaysia	1	1.3
Vietnam	1	1.0

Source: TechInsights, Besi estimates, May 2025

Assembly Market Trends



TechInsights forecasts renewed growth after extended downturn

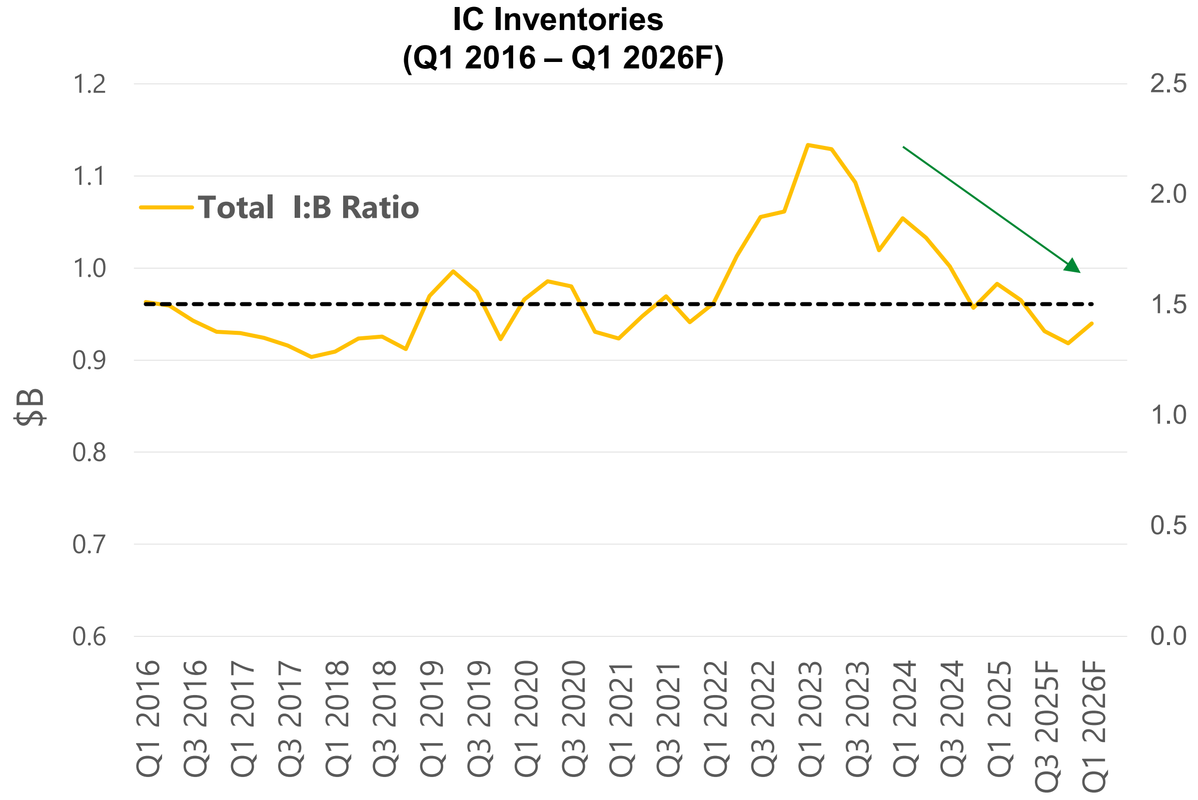
- 75% increase expected 2025-2030
  - Expansion of AI/use cases
  - Recovery of mainstream applications
  - New fabs coming online
- Broad based advanced packaging growth expected

Besi expects to significantly outperform projected assembly market growth

Source: TechInsights, March 2026. Assembly equipment revenue excludes service revenue

Signs of Improving Market Conditions

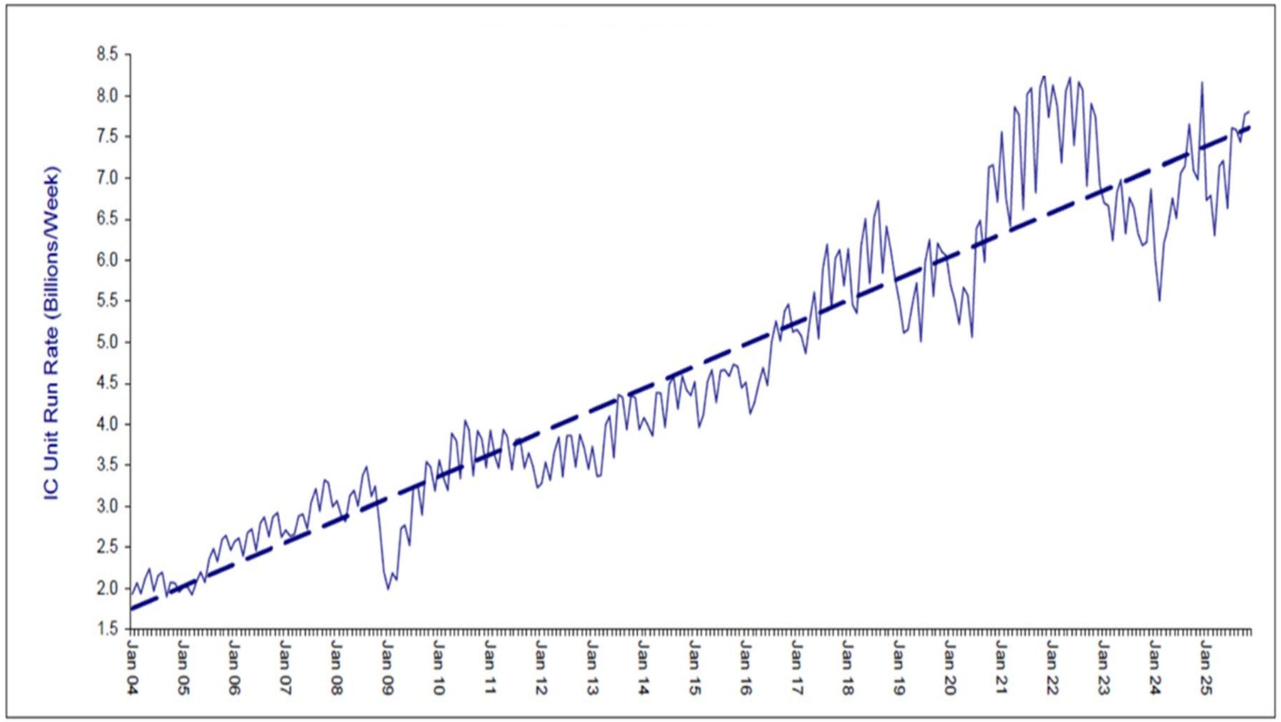
Semi Inventory/Bookings Ratio Reaching Equilibrium



Source: TechInsights, January 2026

IC Unit Growth Trending More Positively Back to Long Term Trend Line

Total Weekly IC Unit Shipments
(2004-2025)



Source: Future Horizons, January 2026

Principal Growth Drivers in Besi's End-User Markets

Computing

Agentic AI

- Datacenters
- Si Photonics
- Edge AI tablets/PC/laptops
- Gaming

Mobile

On Device AI

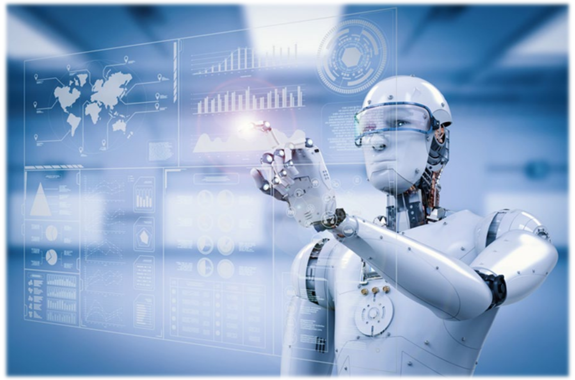
- Adv. cameras & 3D imaging
- 5G advanced → 6G
- Under display biometric ID
- New AR/VR devices

Automotive

Autonomous Driving

- Advanced cameras/sensors
- Vehicle electrification
- SiC & GaN power devices
- Connectivity/infotainment

Industrial / Other

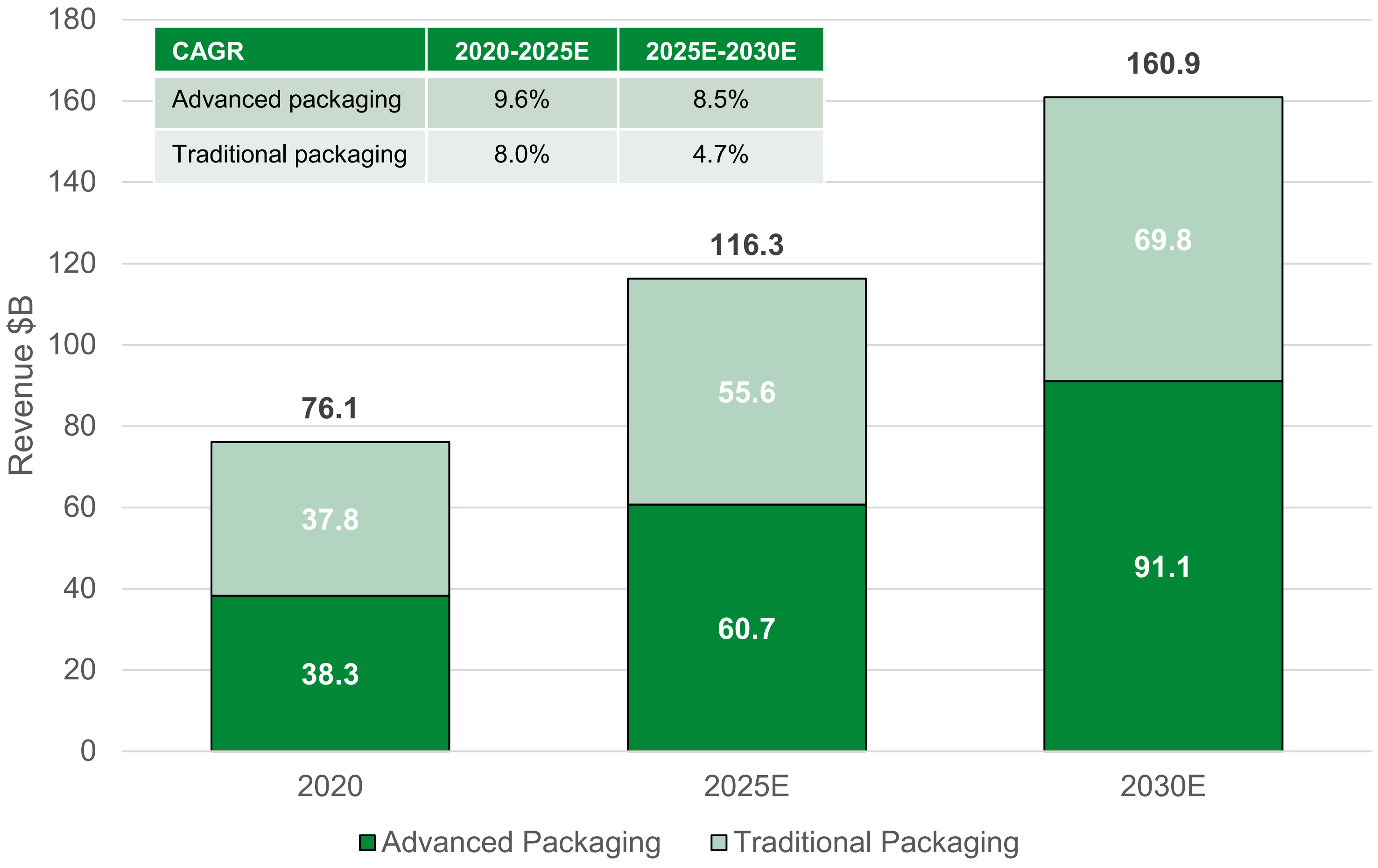


Factory Automation

- Robotics
- Smart grid
- Industrial IoT
- Clean energy

Advanced Packaging Revenue Forecast to Grow Rapidly
2.5D/3D Fastest Growing Segment

CAGR	2020-2025E	2025E-2030E
Advanced packaging	9.6%	8.5%
Traditional packaging	8.0%	4.7%



Source: Yole, August 2025

Besi portfolio well positioned by node size and accuracy

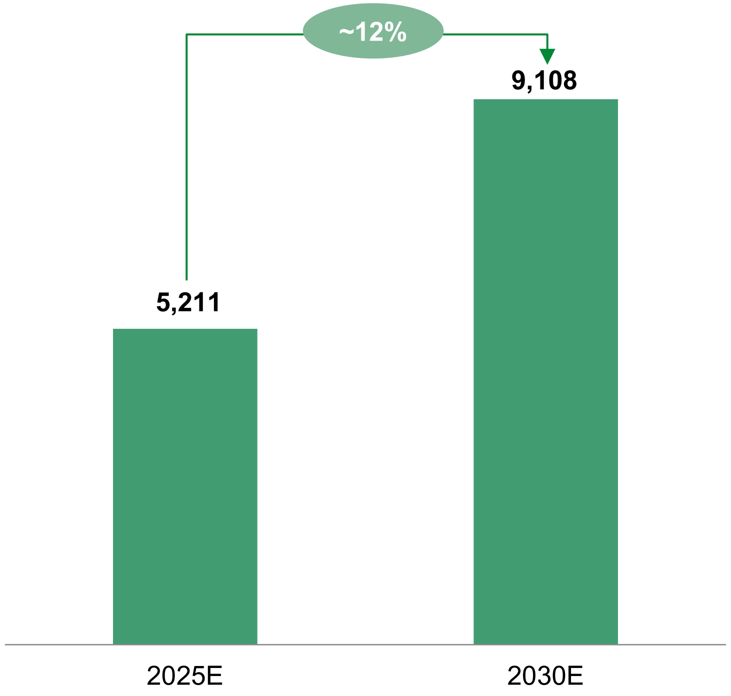
- ~70% of Besi equipment revenue from advanced packaging
- ~60% equipment revenue from advanced die placement (< 7 micron accuracy)
- ~50% of revenue AI-related

Besi Focuses on Highest Growth Segments of Assembly Market

Assembly equipment market

$MM

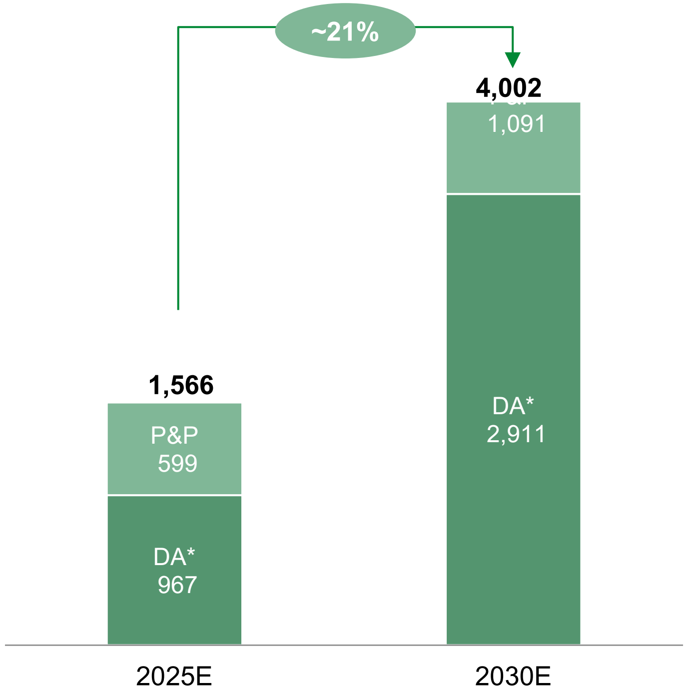
CAGR (2025E-2030E)	
Assembly market	~12%



Besi addressable market

$MM

CAGR (2025E-2030E)	
Die attach	~25%
Packaging and plating	~13%
Total addressable	~21%

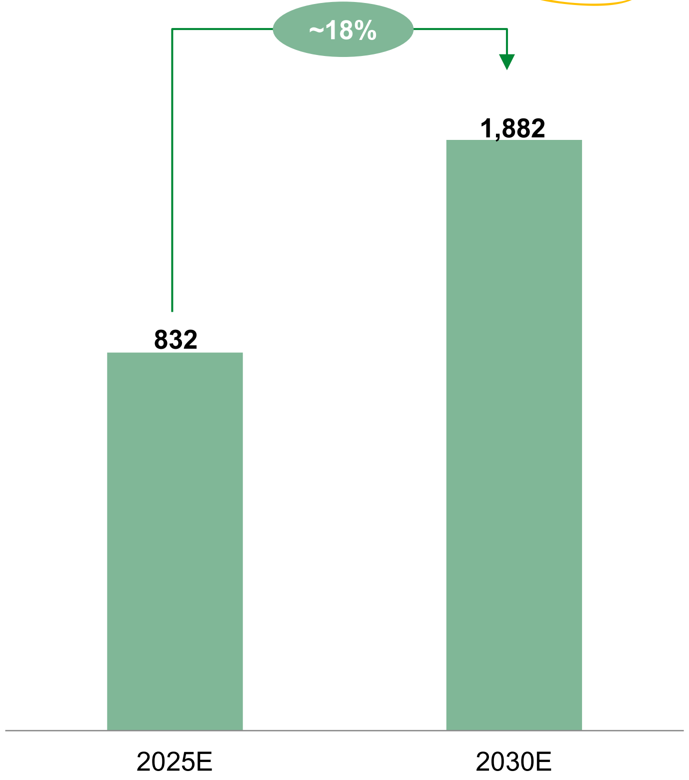


* Excludes TCB in 2025E

Advanced die placement

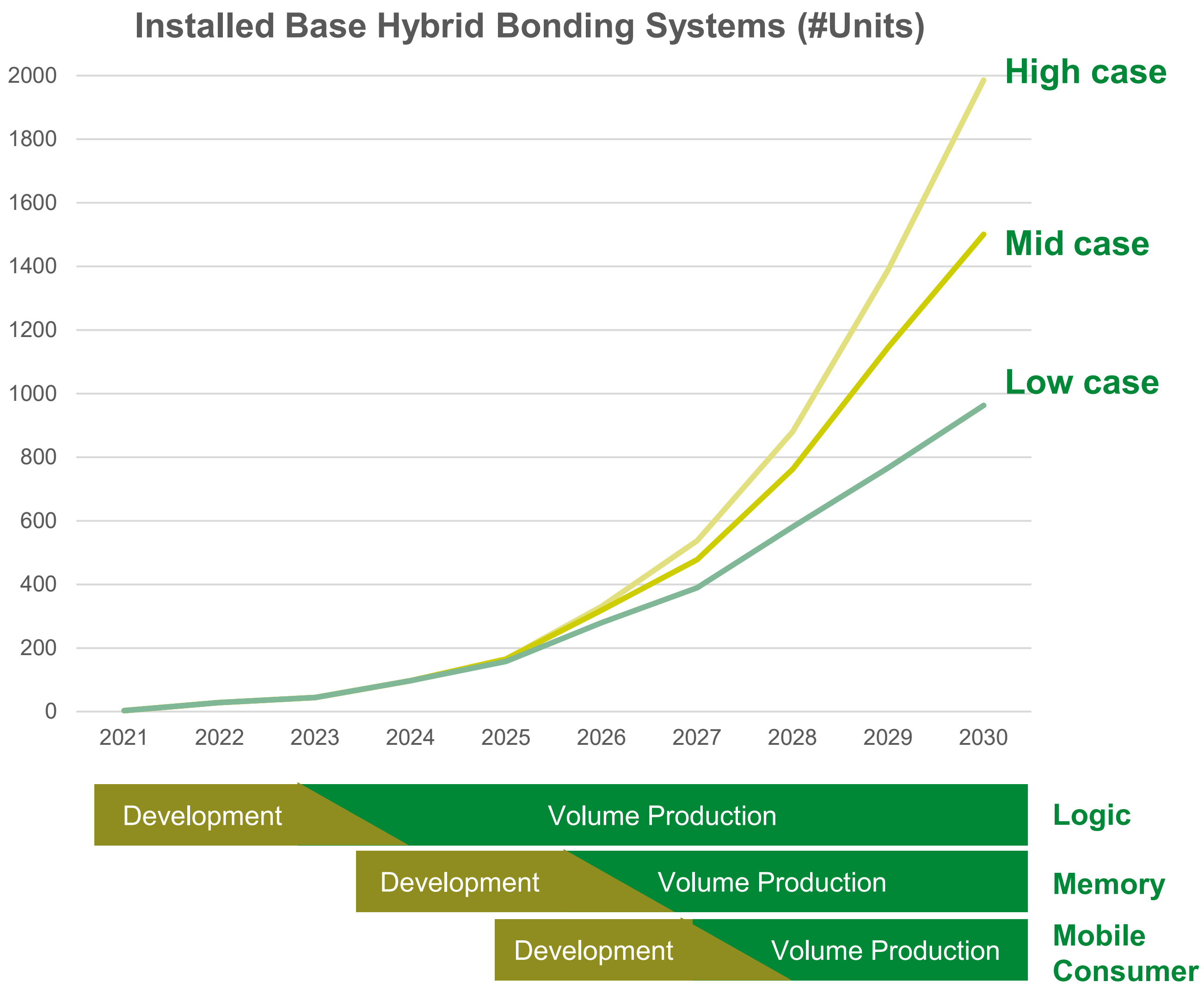
$MM

CAGR (2025E-2030E)	
Advanced die placement	~18%



Source: TechInsights, March 2026

Hybrid Bonding Market Potential – Logic and Memory Cases Confirmed



Source: Besi estimates, June 2025

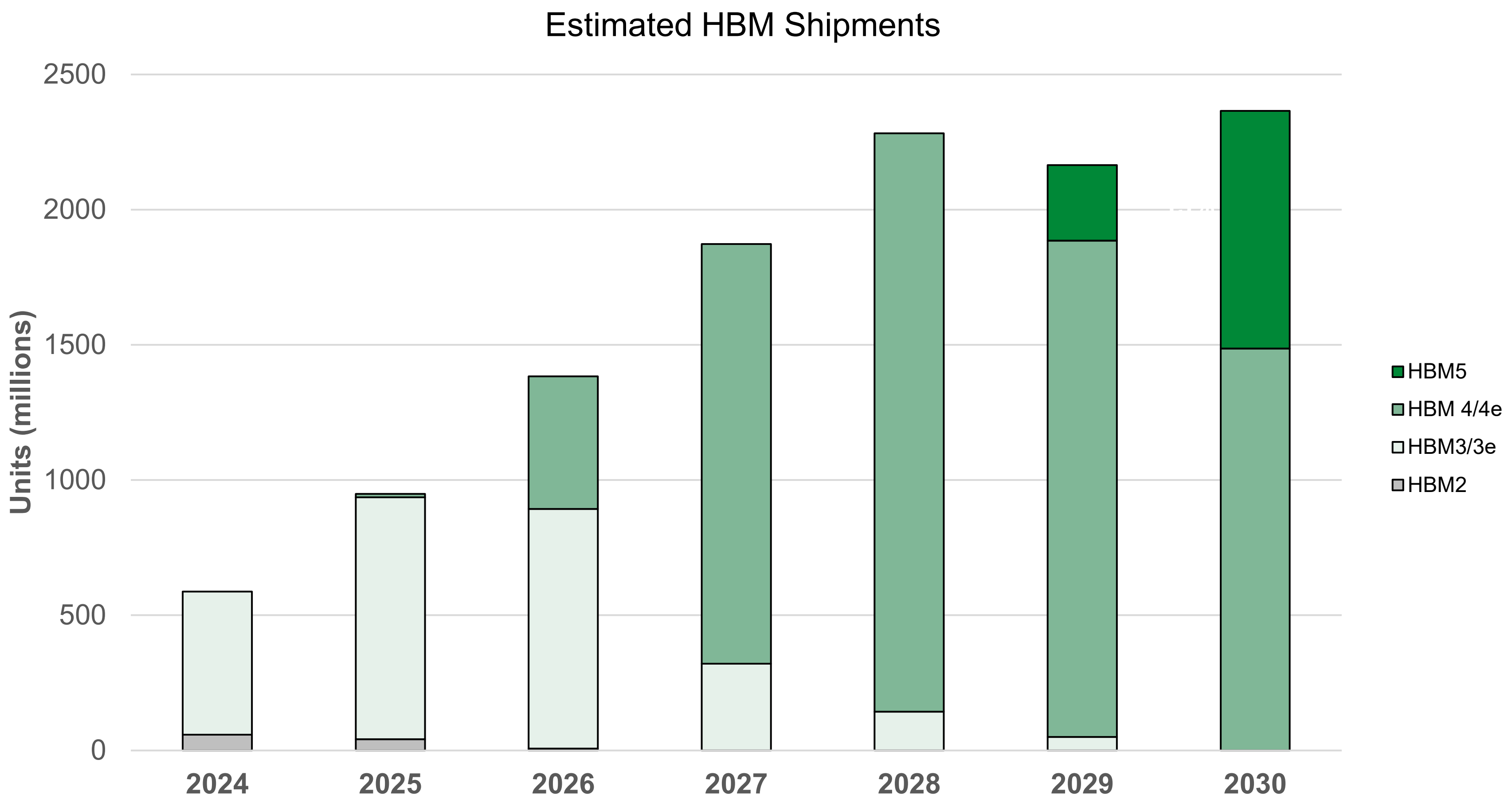
Estimated 960 – 2,000 systems cumulatively by 2030
Up ~7% for low and mid cases vs. 2024 CMD

Low case (logic):
- Logic adoption confirmed
  - AMD and Intel progressing as expected
  - Broadcom adopting SoIC for custom AI ASICs
  - High-end PC/laptop CPUs expected to adopt SoIC by end of 2025
  - Many AI device players in development

Mid case (Memory & CPO):
- Memory adoption confirmed
  - All leading players evaluating both HB and TCB for HBM4
  - First hybrid bonded HBM4e 16 high stacks in 2026
  - HBM 5: Hybrid bonding only
- Co-packed optics moves from upside potential to reality

High case:
- Emerging applications becoming more tangible
  - Smart glasses adopting D2W fusion bonding
  - Micro displays
  - Sensors
  - Smartphones

HBM4/5 Adoption Expected to Accelerate in 2026. Important Drivers for Both Hybrid Bonding and TCB Next Growth



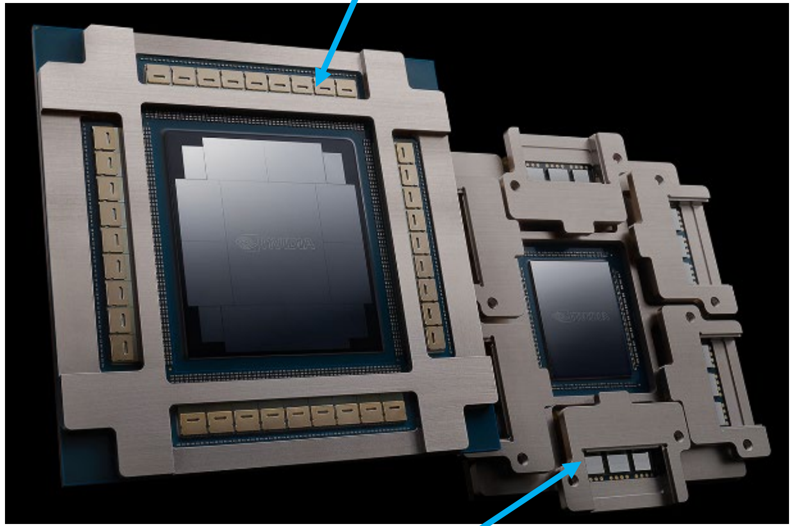
Source: TechInsights, December 2025

Silicon Photonics Another Driver of 2.5D/3D Assembly Growth

NVIDIA confirms Hybrid Bonding adoption in CPO switches

Introduced family of network switch products using co-packaged optics (CPO) in March 2025

Spectrum-X™ Ethernet switch with 36 3D photonics chiplets

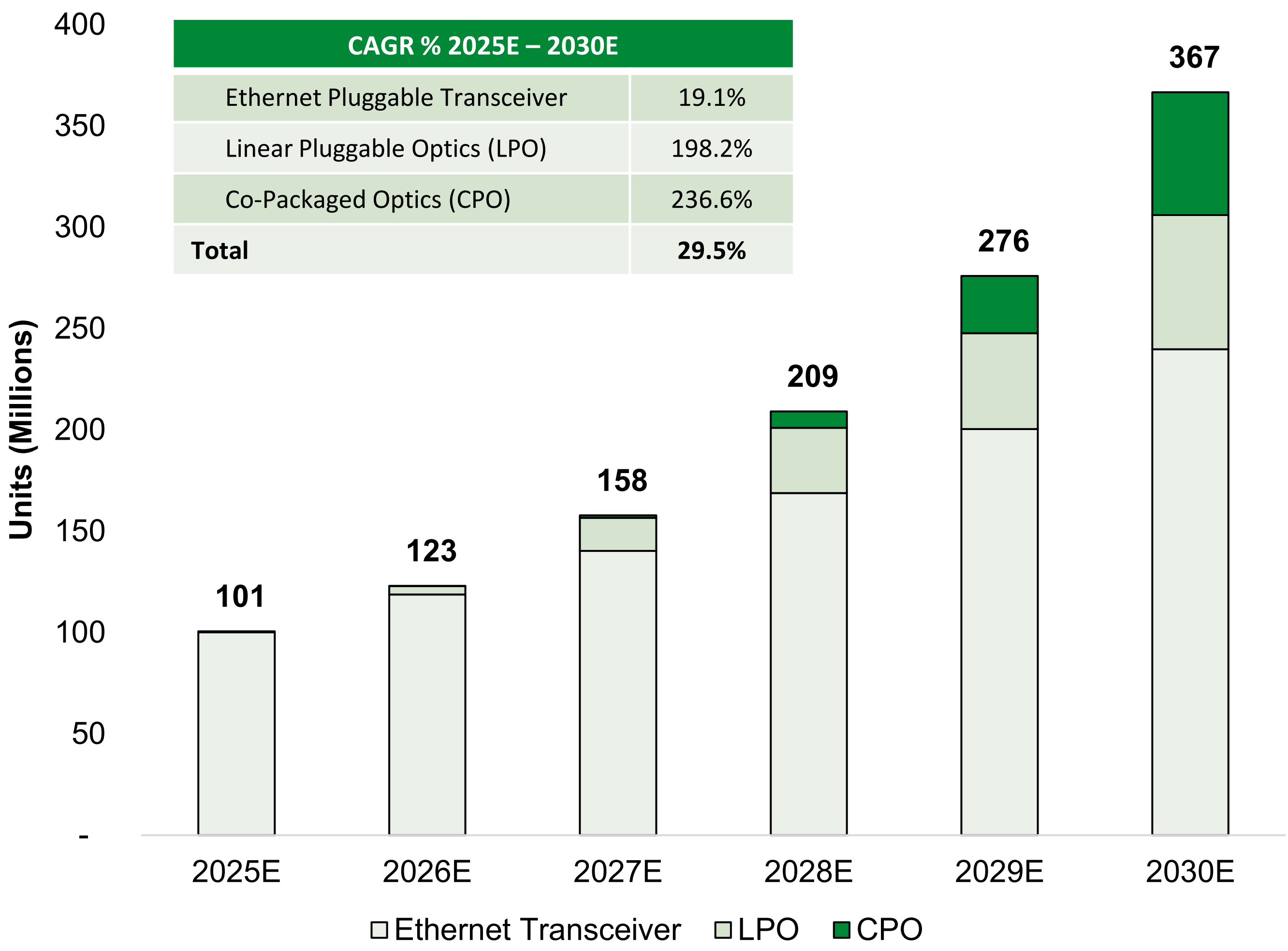


Quantum-X800 InfiniBand switch with 18 3D Photonics chiplets

- TSMC's COUPE technology uses hybrid bonding to assemble the 3D photonic chiplets
- Multiple hybrid bonded chiplets per switch device

Transceiver, LPO and CPO Unit Volume Forecast

CAGR % 2025E – 2030E	
Ethernet Pluggable Transceiver	19.1%
Linear Pluggable Optics (LPO)	198.2%
Co-Packaged Optics (CPO)	236.6%
Total	**29.5%**



Source: LightCounting, October 2025

Besi's Market Opportunity

Generative AI accelerating • Drives investments in next generation devices and applications requiring advanced packaging
New use cases emerging from cloud to edge computing to co-packaged optics
Promise of AI **requires new 2.5D/3D assembly solutions** to further Moore's Law
Advanced packaging one of **key differentiators to realize AI promise** including energy efficient data center performance and new consumer edge AI devices
Accelerated advanced packaging innovation expected in 2026-2030 across logic, memory, consumer and I/O
Expanded R&D investment continues • 2025 gross spending up 11.4% vs. 2024 • New product introductions in 2025-2026 expected to accelerate growth and increase market share
Favorably positioned in highest growth segments: Datacenters, Photonics, AI PCs, Mobile, EV/autonomous driving

III. SUSTAINABILITY

Progress Continues on Besi's Sustainability Agenda

2025 Sustainability Highlights
• Significant progress achieved versus Besi's 2026 sustainability targets
• Successful preparation of ESRS-aligned report for second consecutive year
• Reduction in absolute Scope 1 & 2 and 3 GHG emission levels and fuel consumption
• Scope 1&2 and 3 emissions intensity ratios declined by 16.7% and 4.1%, respectively, versus 2024
• Design-to-X initiative reduced energy consumption of three die attach platforms. Full benefits to be realized in 2026
• Sustainability ratings improved with Sustainalytics, S&P Global and CDP
• Besi Netherlands gained ISO 45001 certification, Seven of eight Besi operations now fully compliant
• Employee survey indicated high levels of participation and engagement. Nine out of ten categories equal to or above high-tech norm
• Improvement in all supply chain engagement indicators versus 2024

Enhanced Sustainability Targets

2026 Milestones

- 85% renewable sources for global energy needs
- 75% reduction in Scope 1 & 2 carbon emissions
- 15% reduction in Scope 3 carbon emissions
- Above-benchmark employee engagement
- 80% vendors to sign GWA and GPC

2030 Targets

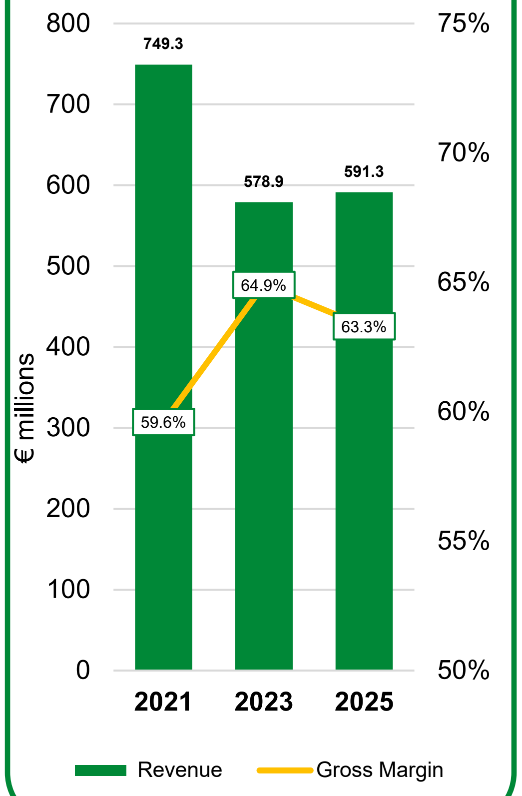
- 100% renewable sources for global energy needs
- Net Zero Scope 1 & 2 carbon emissions
- 20% reduction in Scope 3 carbon emissions
- Achieve revenue objectives with lower environmental impact
- 85% vendors to sign GWA and GPC

Net Zero By 2050

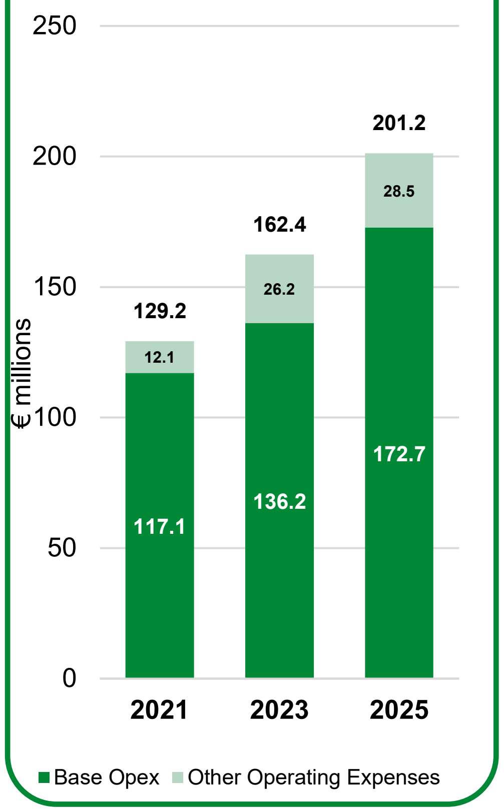
IV. FINANCIAL REVIEW

Key Financial Metrics 2021 – 2025

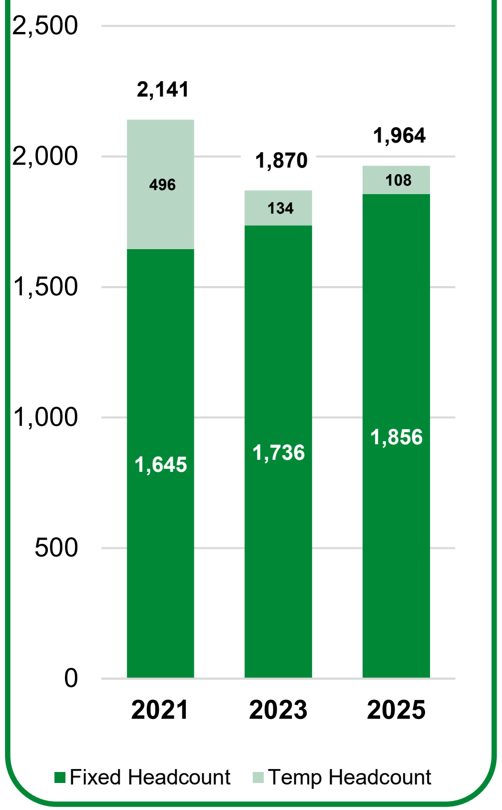
Revenue & Gross Margin



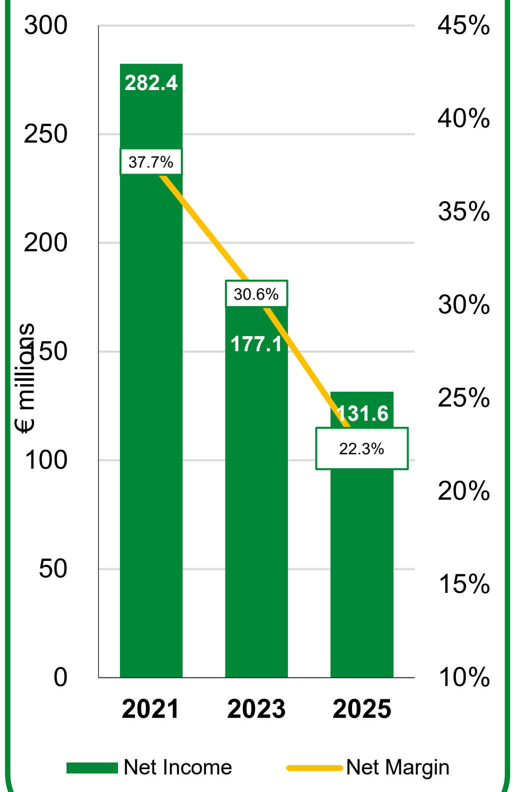
Baseline Opex



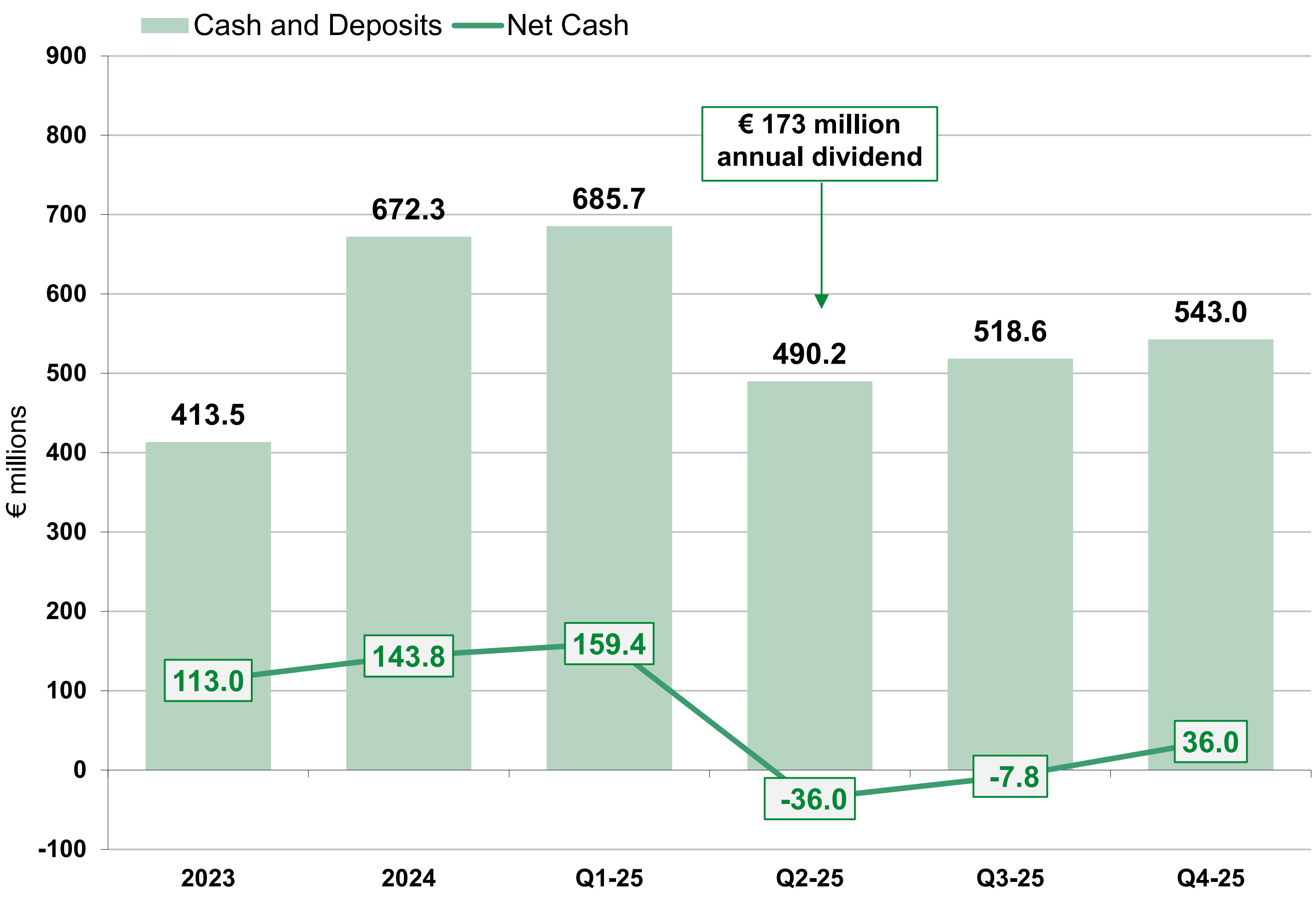
Headcount



Net Income



Strong Liquidity Position Maintained. Net Cash Position Improving



Q4-25 vs. Q3-25

- Cash and deposits of € 543.0 million
  - + € 24.4 million primarily due to:
    - + € 47.9 million cash flow from operations
    - - € 16.1 million share repurchases
    - - € 1.2 million capex
    - - € 5.6 million capitalized R&D
- Net cash of € 36.0 million
  - + € 43.8 million sequentially

Q4-25 vs. Q4-24

- Cash and deposits -19.2% vs. Q4-24
- Capital allocation exceeded cash flow generation
- Purchase of Duiven facility

Capital Allocation

- Capital allocation of € 254.8 million vs. € 251.3 million in 2024
- New € 60 million share repurchase program began in October

Debt Outstanding

- € 175 million 1.875% Convertible Notes due 2029
- € 350 million 4.5% Senior Notes due 2031

Q1-26 Results Above Guidance.

€ millions	Guidance Q1-26*	Q1-26	Δ *Q4-25*	Δ *Q1-25*
Revenue	Up 5-15%	**184.9**	+11.1%	+28.3%
Orders	Significant increase	**269.7**	+7.7%	+104.5%
Gross Margin	63-65%	**63.5%**	-0.4pts	-0.1pts
Opex	Up 10-15%	**53.5**	+7.0%	+1.9%
Operating Income		**63.9**	+13.7%	+62.6%
EBITDA		**73.7**	+11.5%	+58.2%
Net Income		**51.6**	+20.6%	+63.8%
EPS Basic		**0.65**	+20.4%	+62.5%
Net Cash		**103.3**	+67.3	-56.1

* As compared to Q4-25

Increased Hybrid Bonding Use Cases and Products in the News

tsmc	"TSMC says COUPE platform set for production as Samsung outlines Silicon Photonics push" *Digitimes Asia. April 2026* "Taiwan's TSMC advanced packaging fabs on schedule" TSMC is expanding its advanced packaging capacity, especially SoIC hybrid bonding, which enables 3D stacking. *Taiwan News. March 2026*
BROADCOM	"Semiconductor Equipment's Next Gold Mine" Broadcom XDSiP 3.5D platform's core feature is hybrid copper bonding *36Kr Europe. March 2026* "Broadcom paves path for the 200T AI Era" Broadcom highlights optical roadmap, including co-packaged optics and photonics enabled scaling for future AI networks. *Broadcom. March 2026*
SK hynix	"Hybrid bonding expands from logic to memory: SK Hynix, Applied Materials, Besi drive co-optimization to scale next-gen HBM" *Counterpoint. April 2026* "SK Hynix eyes hybrid bonding for HBM5 launch by 2029" *Counterpoint. April 2026*
NVIDIA	"NVIDIA Rubin Ultra and Feynman reportedly to boost TSMC SoIC; Besi, Applied Materials, TEL to benefit" *Trendforce. March 2026* "NVIDIA Feynman GPU gets 3D die-stacking, custom HBM & Next gen Rosa CPU" *Wccftech. March 2026*
SAMSUNG	"Samsung, SK Hynix reportedly ramp hybrid bonding push for next-gen HBM" *Digitimes Asia. April 2026* "Samsung unveils HBM4E, showcasing comprehensive AI solutions, NVIDIA partnership and Vision at NVIDIA GTC 2026" *Samsung. March 2026* "Samsung Electronics launches silicon photonics foundry business." Building production ready photonic integrated circuits now with aim to scale toward co-packaged optics by 2030" *Design & Reuse. April 2026*
Micron	"How Micron is Looking to Win the HBM Wars" Micron frames hybrid bonding as part of its 2026 HBM4 transition. *Forbes. April 2026*
Apple	"Apple M5 Pro and M5 Max to feature 3D hybrid bonding". *Netfox. March 2026*
COHERENT	"Coherent demonstrates multiple co-packaged optics technologies at OFC 2026." Coherent to show how photonics stack can meet bandwidth and efficiency needs of AI datacenters. *Coherent. March 2026*
AMD	"Engineering the Future of AI" AMD has ongoing innovation in 2.5D, 3D and hybrid bonding as part of heterogeneous packaging for future Instinct accelerators *AMD Blog. November 2025*

Guidance Q2-26 & H1-26

€ in millions

Q2-26

	Revenue	Gross Margin	Total Operating Expenses
Q1-26	€ 184.9	63.5%	€ 53.5
Q2-26	+30% to +40%	64%-66%	0% to +10%

HY1-26

	Revenue	Gross Margin	Total Operating Expenses
HY1-25	€ 292.2	63.4%	€ 102.7
HY1-26*	+49%	~64.4%	+7%

* At midpoint of Q2-26 guidance